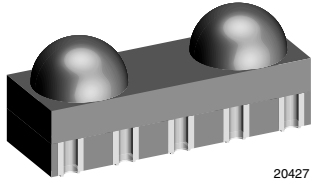# IR Receiver Modules for Remote Control Systems

MECHANICAL DATA

Pinning

1, 4, 5 = GND, 2 = V_S, 3 = OUT

FEATURES

- Very low supply current
- Photo detectors and preamplifier in one package
- Internal filter for PCM frequency
- Supply voltage: 2.5 V to 5.5 V
- Improved immunity against ambient light
- Capable of side or top view
- Two lenses for high sensitivity and wide receiving angle
- Compliant to RoHS Directive 2002/95/EC and in accordance to WEEE 2002/96/EC
- Insensitive to supply voltage ripple and noise

RoHS COMPLIANT

DESCRIPTION

The TSOP853.. and TSOP855.. series are two lens miniaturized receiver modules for infrared remote control systems. One PIN diode per lens and a preamplifier are assembled on a PCB, the epoxy lens cap is designed as an IR filter.

The demodulated output signal can be directly decoded by a microprocessor. The TSOP853.. is optimized to better suppress spurious pulses from energy saving fluorescent lamps. The TSOP855.. has an excellent noise suppression. It is immune to dimmed LCD backlighting and any fluorescent lamps. AGC3 and AGC5 may also suppress some data signals in case of continuous transmission.

This component has not been qualified according to automotive specifications.
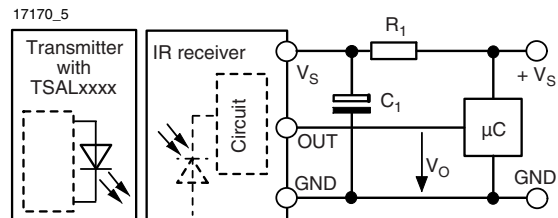
PARTS TABLE

CARRIER FREQUENCY	NOISY ENVIRONMENTS AND SHORT BURSTS (AGC3)	VERY NOISY ENVIRONMENTS AND SHORT BURSTS (AGC5)
30 kHz	TSOP85330	TSOP85530
33 kHz	TSOP85333	TSOP85533
36 kHz	TSOP85336	TSOP85536
38 kHz	TSOP85338	TSOP85538
40 kHz	TSOP85340	TSOP85540
56 kHz	TSOP85356	TSOP85556

BLOCK DIAGRAM
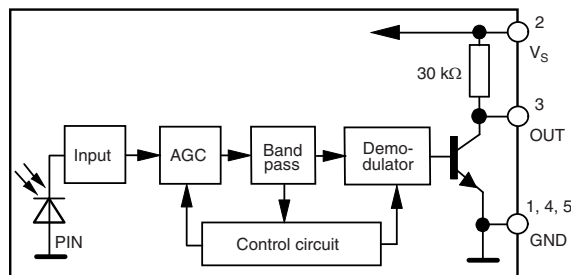
APPLICATION CIRCUIT

R_1 and C_1 are recommended for protection against EOS. Components should be in the range of 33 Ω < R_1 < 1 kΩ, C_1 > 0.1 µF.

ABSOLUTE MAXIMUM RATINGS

PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Supply voltage		V_S	- 0.3 to + 6	V
Supply current		I_S	3	mA
Output voltage		V_O	- 0.3 to (V_S + 0.3)	V
Output current		I_O	5	mA
Junction temperature		T_j	100	°C
Storage temperature range		T_{stg}	- 25 to + 85	°C
Operating temperature range		T_{amb}	- 25 to + 85	°C
Power consumption	$T_{amb} \leq 85$ °C	P_{tot}	10	mW
Soldering temperature		T_{sd}	260	°C

Note

- Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect the device reliability.

ELECTRICAL AND OPTICAL CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)

PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Supply voltage		V_S	2.5		5.5	V
Supply current	V_S = 3.3 V, E_v = 0	I_{SD}	0.27	0.35	0.45	mA
	E_v = 40 klx, sunlight	I_{SH}		0.45		mA
Transmission distance	E_v = 0, IR diode TSAL6200, I_F = 250 mA, test signal see fig. 1	d		45		m
Output voltage low	I_{OSL} = 0.5 mA, E_e = 0.7 mW/m^2, test signal see fig. 1	V_{OSL}			100	mV
Minimum irradiance	Pulse width tolerance: t_{pi} - 5/f_o < t_{po} < t_{pi} + 6/f_o, test signal see fig. 1	$E_{e\ min.}$		0.1	0.25	mW/m^2
Maximum irradiance	t_{pi} - 5/f_o < t_{po} < t_{pi} + 6/f_o, test signal see fig. 1	$E_{e\ max.}$	30			W/m^2
Directivity	Angle of half transmission distance	$\varphi_{1/2}$		± 50		deg

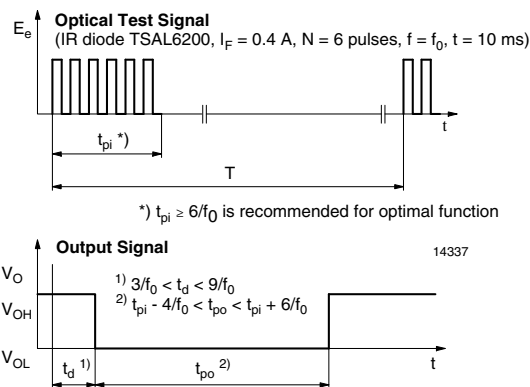## TYPICAL CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)
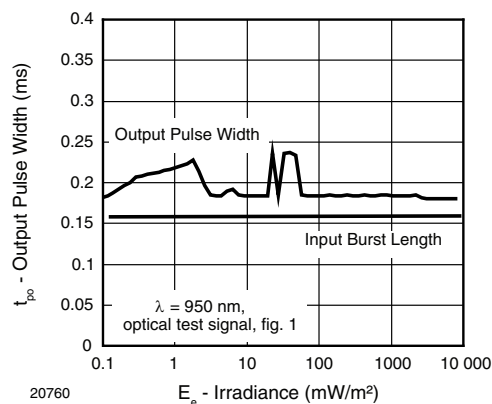

Fig. 1 - Output Active Low

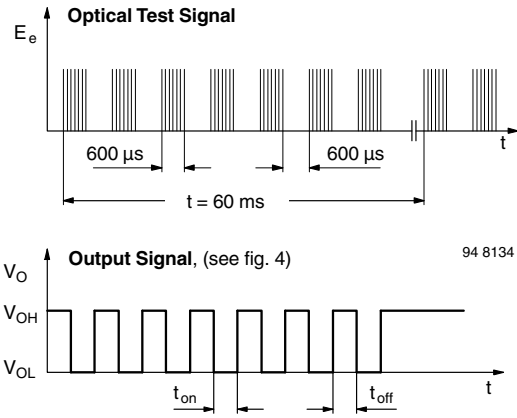Fig. 2 - Pulse Length and Sensitivity in Dark Ambient
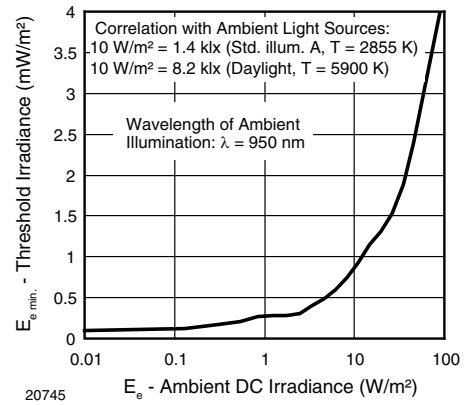
Optical Test Signal

Fig. 3 - Output Function

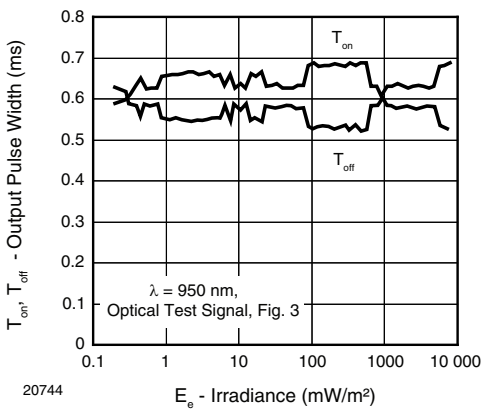Fig. 6 - Sensitivity in Bright Ambient
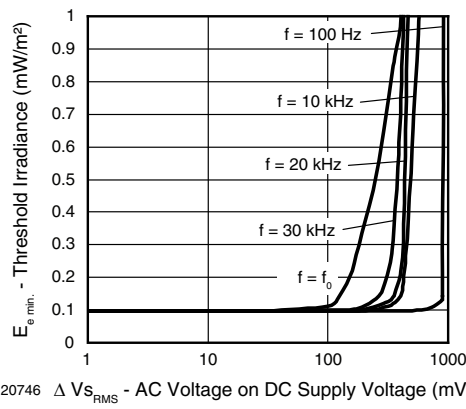
Fig. 4 - Output Pulse Diagram

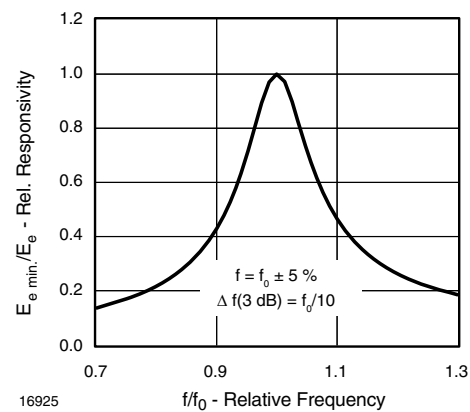Fig. 7 - Sensitivity vs. Supply Voltage Disturbances

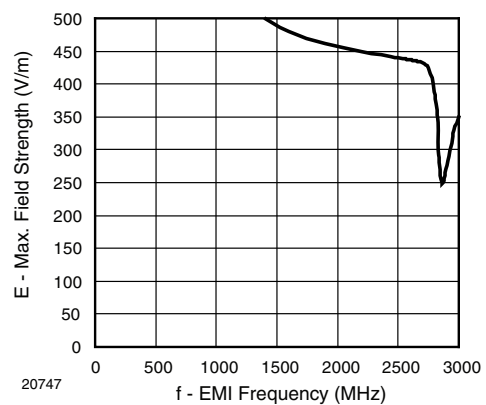Fig. 5 - Frequency Dependence of Responsivity

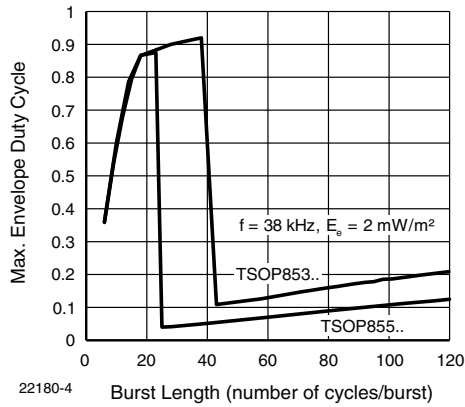Fig. 8 - Sensitivity vs. Electric Field Disturbances

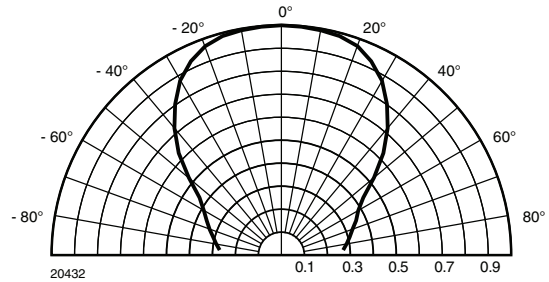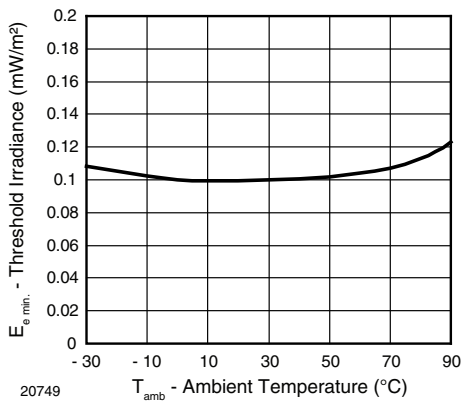Fig. 9 - Maximal Envelope Duty Cycle vs. Burst Length

Fig. 12 - Directivity

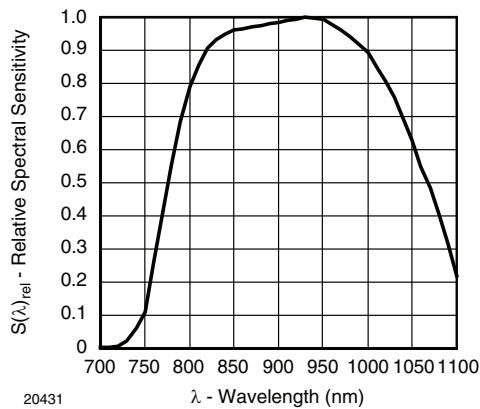Fig. 10 - Sensitivity vs. Ambient Temperature

Fig. 11 - Relative Spectral Sensitivity vs. Wavelength

SUITABLE DATA FORMAT

The TSOP853.. and TSOP855.. series are designed to suppress spurious output pulses due to noise or disturbance signals. Data and disturbance signals can be distinguished by the devices according to carrier frequency, burst length and envelope duty cycle. The data signal should be close to the band-pass center frequency (e.g. 38 kHz) and fulfill the conditions in the table below.

When a data signal is applied to the TSOP853.. and TSOP855.. series in the presence of a disturbance signal, the sensitivity of the receiver is reduced to insure that no spurious pulses are present at the output. Some examples of disturbance signals which are suppressed are:

- DC light (e.g. from tungsten bulb or sunlight)

- Continuous signals at any frequency

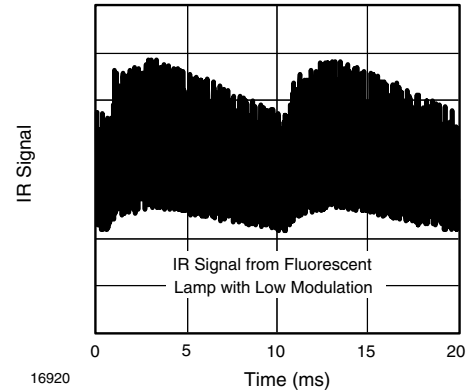- Modulated noise from fluorescent lamps with electronic ballasts

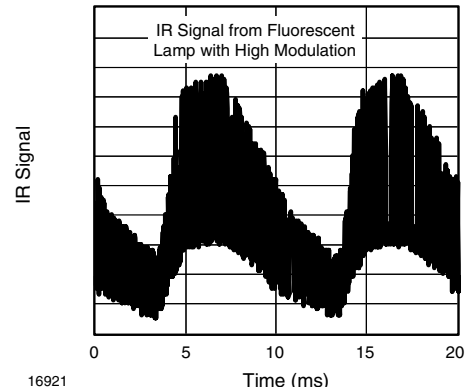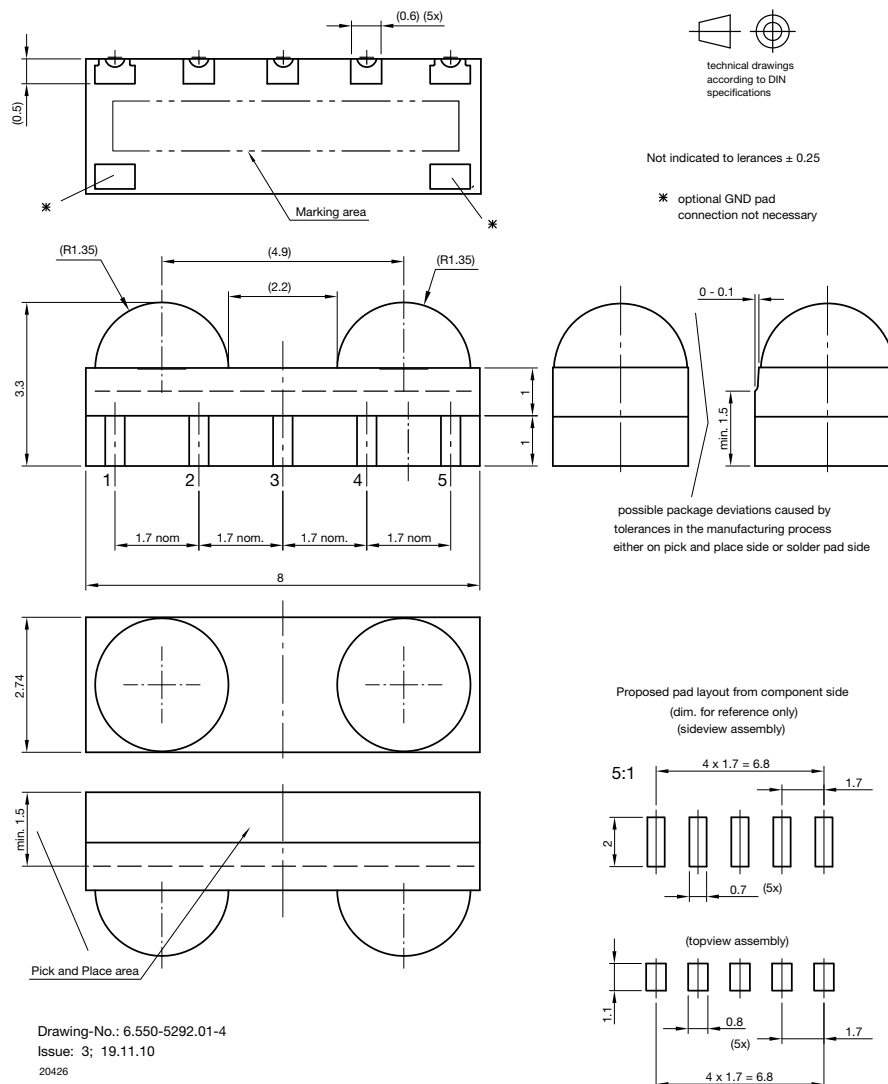Fig. 13 - IR Signal from Fluorescent Lamp
with Low Modulation

Fig. 14 - IR Signal from Fluorescent Lamp
with High Modulation

	TSOP853..	TSOP855..
Minimum burst length	6 cycles/burst	6 cycles/burst
After each burst of length a minimum gap time is required of	6 to 35 cycles ≥ 10 cycles	6 to 24 cycles ≥ 10 cycles
For bursts greater than a minimum gap time in the data stream is needed of	35 cycles > 6 x burst length	24 cycles > 25 ms
Maximum number of continuous short bursts/second	2000	2000
Recommended for NEC code	yes	yes
Recommended for RC5/RC6 code	yes	yes
Recommended for Sony code	no	no
Recommended for RCMM code	yes	yes
Recommended for r-step code)	yes	yes
Recommended for XMP code	yes	yes
Suppression of interference from fluorescent lamps	Even critical disturbance signals are suppressed (examples: signal pattern of fig. 13 and fig. 14)	Even critical disturbance signals are suppressed (examples: signal pattern of fig. 13 and fig. 14)

Note

- For data formats with long bursts (more than 10 carrier cycles) please see the datasheet for TSOP852.., TSOP854..

PACKAGE DIMENSIONS in millimeters

technical drawings according to DIN specifications

Not indicated to lerances ± 0.25

✳ optional GND pad connection not necessary

Marking area

possible package deviations caused by tolerances in the manufacturing process either on pick and place side or solder pad side

Proposed pad layout from component side (dim. for reference only) (sideview assembly)

5:1   4 x 1.7 = 6.8   1.7

0.7 (5x)

(topview assembly)

0.8
(5x)   1.7

4 x 1.7 = 6.8

Pick and Place area

Drawing-No.: 6.550-5292.01-4
Issue: 3; 19.11.10
20426

ASSEMBLY INSTRUCTIONS

Reflow Soldering

• Reflow soldering must be done within 72 h while stored under a max. temperature of 30 °C, 60 % RH after opening the dry pack envelope

• Set the furnace temperatures for pre-heating and heating in accordance with the reflow temperature profile as shown in the diagram. Excercise extreme care to keep the maximum temperature below 260 °C. The temperature shown in the profile means the temperature at the device surface. Since there is a temperature difference between the component and the circuit board, it should be verified that the temperature of the device is accurately being measured

• Handling after reflow should be done only after the work surface has been cooled off

Manual Soldering

• Use a soldering iron of 25 W or less. Adjust the temperature of the soldering iron below 300 °C

• Finish soldering within 3 s

• Handle products only after the temperature has cooled off

VISHAY LEAD (Pb)-FREE REFLOW SOLDER PROFILE

19800

max. 2 cycles allowed
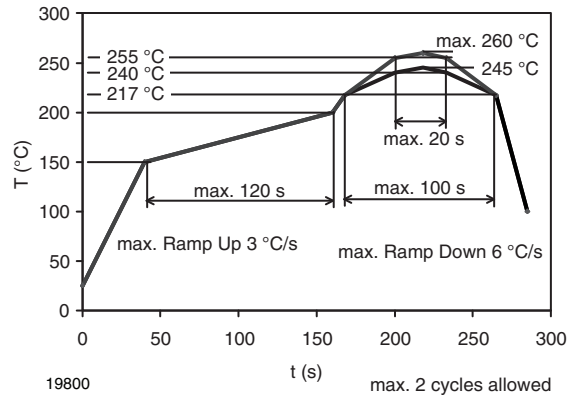
TAPING VERSION TSOP..TR DIMENSIONS in millimeters

technical drawings according to DIN specifications
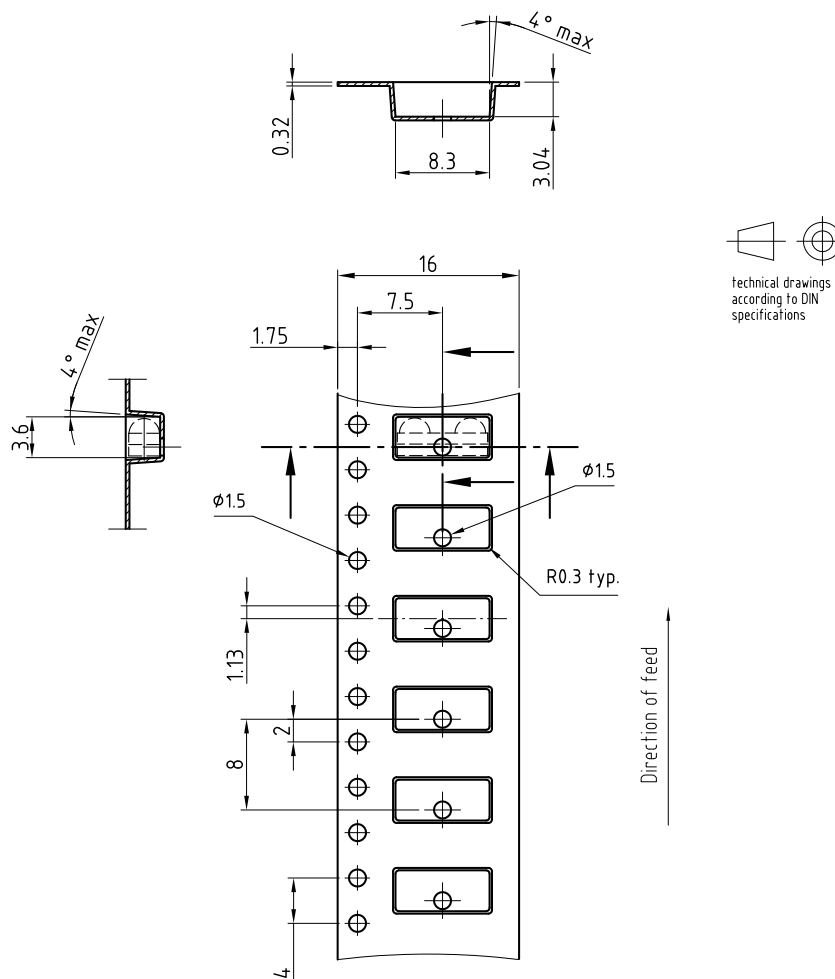
Drawing-No.: 9.700-5316.01-4
Issue: 1; 12.02.07
20628

TAPING VERSION TSOP..TT DIMENSIONS in millimeters
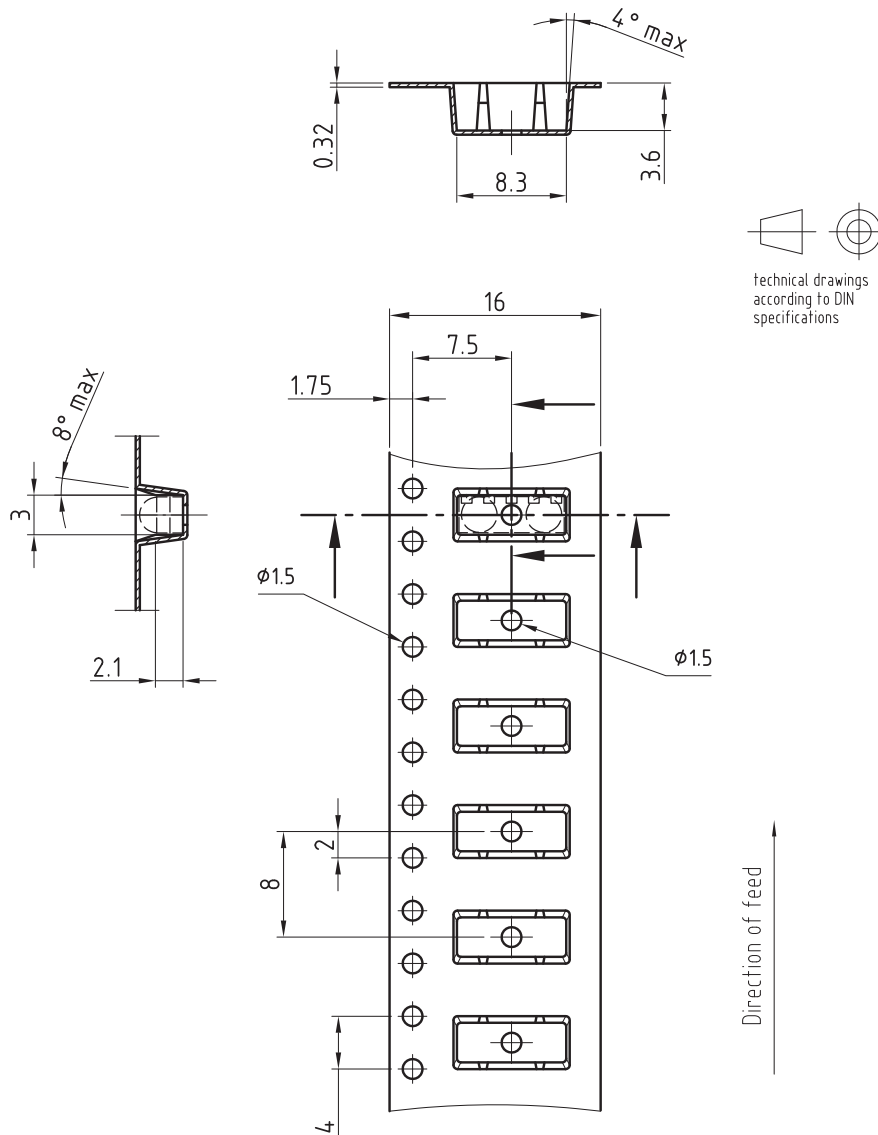
Drawing-No.: 9.700-5317.01-4
Issue: 2; 10.04.08
20629

LABEL

### Standard bar code labels for finished goods

The standard bar code labels are product labels and used for identification of goods. The finished goods are packed in final packing area. The standard packing units are labeled with standard bar code labels before transported as finished goods to warehouses. The labels are on each packing unit and contain Vishay Semiconductor GmbH specific data.

VISHAY SEMICONDUCTOR GmbH STANDARD BAR CODE PRODUCT LABEL (finished goods)		
PLAIN WRITING	**ABBREVIATION**	**LENGTH**
Item-description	-	18
Item-number	INO	8
Selection-code	SEL	3
LOT-/serial-number	BATCH	10
Data-code	COD	3 (YWW)
Plant-code	PTC	2
Quantity	QTY	8
Accepted by	ACC	-
Packed by	PCK	-
Mixed code indicator	MIXED CODE	-
Origin	xxxxxxx+	Company logo
Long bar code top	**Type**	**Length**
Item-number	N	8
Plant-code	N	2
Sequence-number	X	3
Quantity	N	8
Total length	-	21
Short bar code bottom	**Type**	**Length**
Selection-code	X	3
Data-code	N	3
Batch-number	X	10
Filter	-	1
Total length	-	17

DRY PACKING

The reel is packed in an anti-humidity bag to protect the devices from absorbing moisture during transportation and storage.
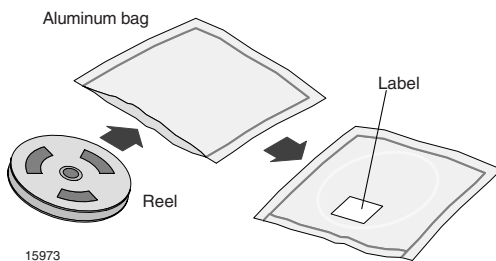
FINAL PACKING

The sealed reel is packed into a cardboard box. A secondary cardboard box is used for shipping purposes.

RECOMMENDED METHOD OF STORAGE

Dry box storage is recommended as soon as the aluminum bag has been opened to prevent moisture absorption. The following conditions should be observed, if dry boxes are not available:

• Storage temperature 10 °C to 30 °C

• Storage humidity ≤ 60 % RH max.

After more than 72 h under these conditions moisture content will be too high for reflow soldering.
In case of moisture absorption, the devices will recover to the former condition by drying under the following condition:
192 h at 40 °C + 5 °C/- 0 °C and < 5 % RH (dry air/nitrogen) or
96 h at 60 °C + 5 °C and < 5 % RH for all device containers or
24 h at 125 °C + 5 °C not suitable for reel or tubes.
An EIA JEDEC standard JESD22-A112 level 4 label is included on all dry bags.
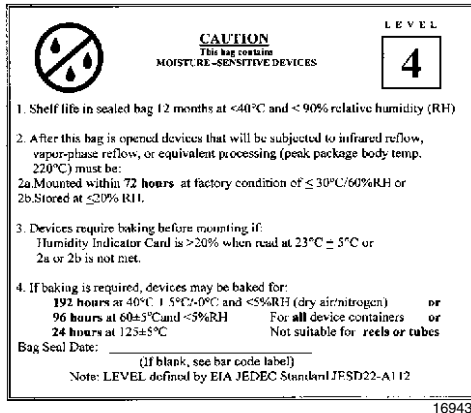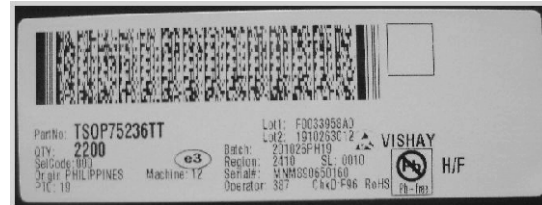

Example of JESD22-A112 level 4 label

ESD PRECAUTION

Proper storage and handling procedures should be followed to prevent ESD damage to the devices especially when they are removed from the antistatic shielding bag. Electro-static sensitive devices warning labels are on the packaging.

VISHAY SEMICONDUCTORS STANDARD BAR CODE LABELS

The Vishay Semiconductors standard bar code labels are printed at final packing areas. The labels are on each packing unit and contain Vishay Semiconductors specific data.

BAR CODE PRODUCT LABEL EXAMPLE:

22178

Disclaimer

All product specifications and data are subject to change without notice.

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